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Sheet

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1. Name of conveying party(ies):

Lee, Keun hyuk

1-10-03

Additional name(s) of conveying party(ies) attached? ☒ Yes ☐ No.

3. Nature of conveyance:

- ☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other: _____

Execution Date: December 17, 2002

2. Name and address of receiving party(ies)

Name: Fairchild Korea Semiconductor Ltd.

Internal Address: _____

Street Address: 82-3 Dondan-dong, Wonmi-ku, Puchon

City: Kyungki-do Country: Korea ZIP: _____

Additional name(s) and address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No(s): 10/265,081

B. Patent No(s): _____

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Patrick R. Jewik
 TOWNSEND AND TOWNSEND AND CREW LLP
 Two Embarcadero Center, 8th Floor
 San Francisco, California 94111-3834
 (415) 576-0200

6. Total number of applications and patents involved 1

7. Total fee (37 CFR 3.41): -----\$40.00

- ☐ Enclosed
☒ Authorized to be charged to deposit account

8. Deposit account number: 20-1430

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Patrick R. Jewik

Name of Person Signing
 Atty. Reg. No. 40,456

1/3/02
 Date

Total number of pages including cover sheet, attachments and document 4

Mail documents to be recorded with required cover sheet information to:
 Commissioner of Patents and Trademarks, Box Assignments
 Washington, D.C. 20231

01/16/2003 LMUELLER 00000266 201430 10265081

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PATENT
 REEL: 013664 FRAME: 0704

1. Additional name(s) of conveying party(ies):
(Continued from Page 1)

Kim, Ji-hwan
Chung, Dae-woong
Jeon, O-seob

2. Additional name(s) and address(es) of receiving party(ies):
(Continued from Page 1)

3. Additional application number(s) or patent number(s):
(Continued from Page 1)

A. Patent Application No.(s)

B. Patent No.(s)

SF 1419590 v1

ASSIGNMENT OF PATENT APPLICATION

WHEREAS, Keun hyuk Lee of 74-91, Jangwi 2-dong, Seongbuk-gu, Seoul, Korea, South; Ji-hwan Kim of 208-404, Daewoo Apt., 296, Gochuk-dong Guro-gu, Seoul, Korea, South; Dae-woong Chung of 1522-101 Hanarum Donga Apt, Sang 1-dong, Wonmi-gu, Bucheon-city, Kyungki-do, Seoul, Korea, South; O-seob Jeon of 2-38, Daelim Apt., Yeonhei 3-dong, Seodaemun-gu, Seoul, Korea, South hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: SEMICONDUCTOR POWER PACKAGE MODULE

Date(s) of Execution: December 17, 2002

Filing Date: October 4, 2002

Application No.: 10/265,081; and

WHEREAS, Fairchild Korea Semiconductor Ltd. located at 82-3, Dondan-dong, Wonmi-ku, Puchon, Kyungki-do, Korea, hereinafter referred to as "ASSIGNEE," is desirous of acquiring ASSIGNORS' interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said Assignees, and Assignees' successors and assigns, all their right, title and interest in and to the said invention and application, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignees as fully and exclusively as it would have been held and enjoyed by said Assignors had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, 8th Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: Dec. 17, 2002

O-seob Jeon
O-seob Jeon

Dated: Dec 17, 2002

Sang Kim
Witness

Dated: Dec. 17, 2002

Dae-woong Chung
Dae-woong Chung

Dated: Dec 17, 2002

Sang Kim
Witness

Dated: Dec. 17, 2002

Ji-hwan Kim
Ji-hwan Kim

Dated: Dec 17, 2002

Sang Kim
Witness

Dated: Dec. 17, 2002

Keun-Hyuk Lee
Keun hyuk Lee

Dated: Dec 17, 2002

Sang Kim
Witness

SF 1410471 v1